


590 High Temperature Masking Tape	Ref: 590	
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1. Product Description / Application

Rev Dec 18

Polyimide Masking Tape - 260°C

Our 590 Polyimide Tape is the industry standard for use when masking whilst Soldering, Circuit Board Insulation and Hot Air Levelling, as well as traditional Powder Coating and E-Coating.

At 88 microns thick, our 590 has a maximum temperature resistance of 290°C. A low tack silicone adhesive system ensures that the tape will leave no residue on the surface once removed and the high quality polyimide film means the tape will not shrink in application.

2. Key Characteristics

- 88 microns thick
- 260°C temperature resistance
- A low tack silicone adhesive system ensures that the tape will leave no residue
- High quality polyimide film means the tape will not shrink

4. Product Data

Temperature Resistance	260°C
Backing	25.4-micron Polyimide Film
Adhesive	Silicone
Overall Thickness	88 micron
Breaking Strength	5.4kg per cm
Elongation	60%
Adhesion to steel	0.3kg per cm
Dielectric strength	7.500 volts
Insulation Class	H

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